

SOT1049-3

plastic, extremely thin quad flat package; 10 terminals; 0.5 mm pitch; 1.55 mm x 2 mm x 0.5 mm body

27 June 2025

Package information



1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	XQFN10
Package type industry code	XQFN10
Package style descriptive code	XQFN (extremely thin quad flatpack; no leads)
Package body material type	P (plastic)
JEDEC package outline code	MO255
Mounting method type	S (surface mount)
Issue date	25-06-2025
Manufacturer package code	SOT1049

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	1.45	1.55	1.65	mm
package width	1.9	2	2.1	mm
seated height	0.47	0.485	0.5	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	10	-	

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2 Package outline

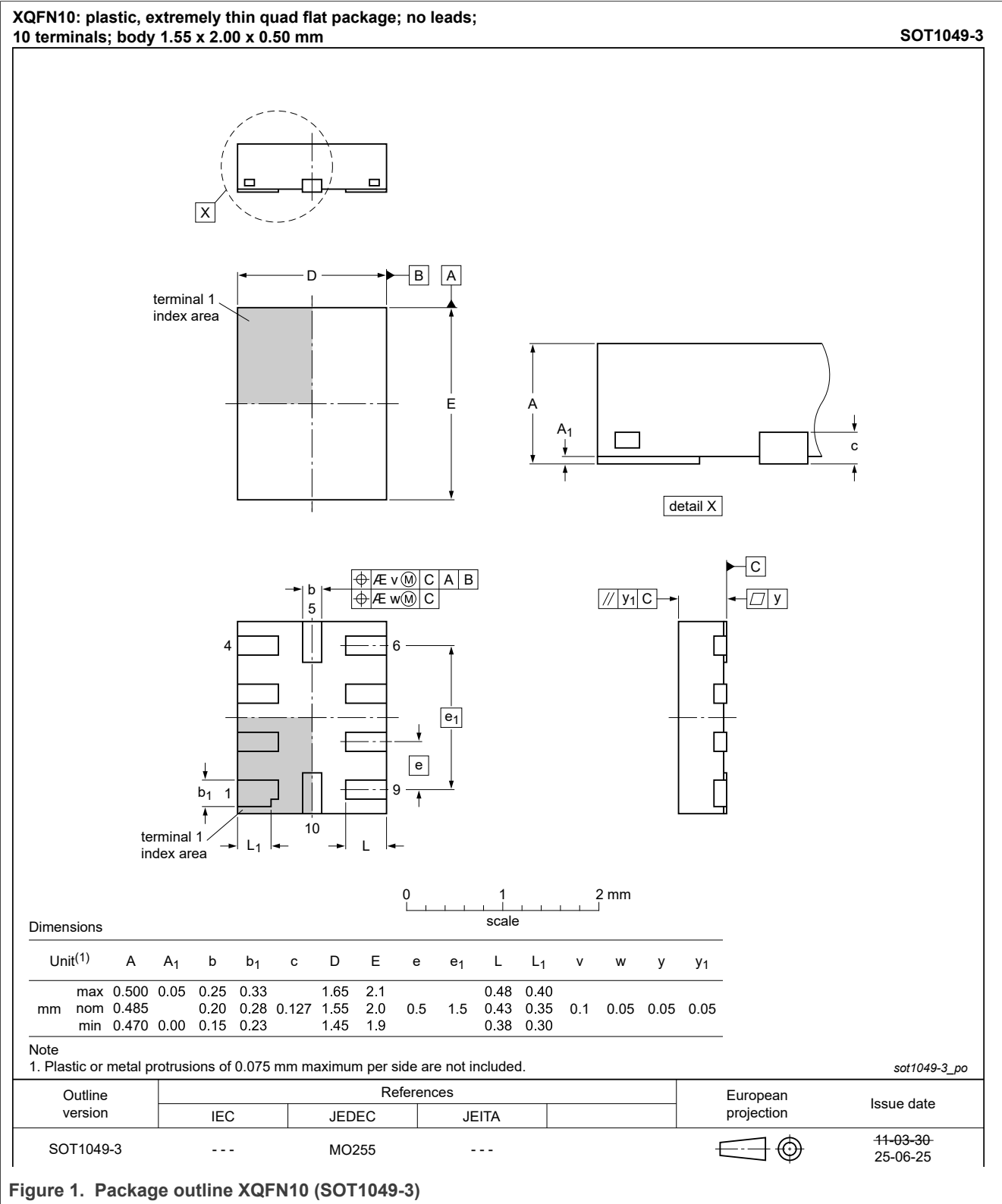


Figure 1. Package outline XQFN10 (SOT1049-3)

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3 Soldering

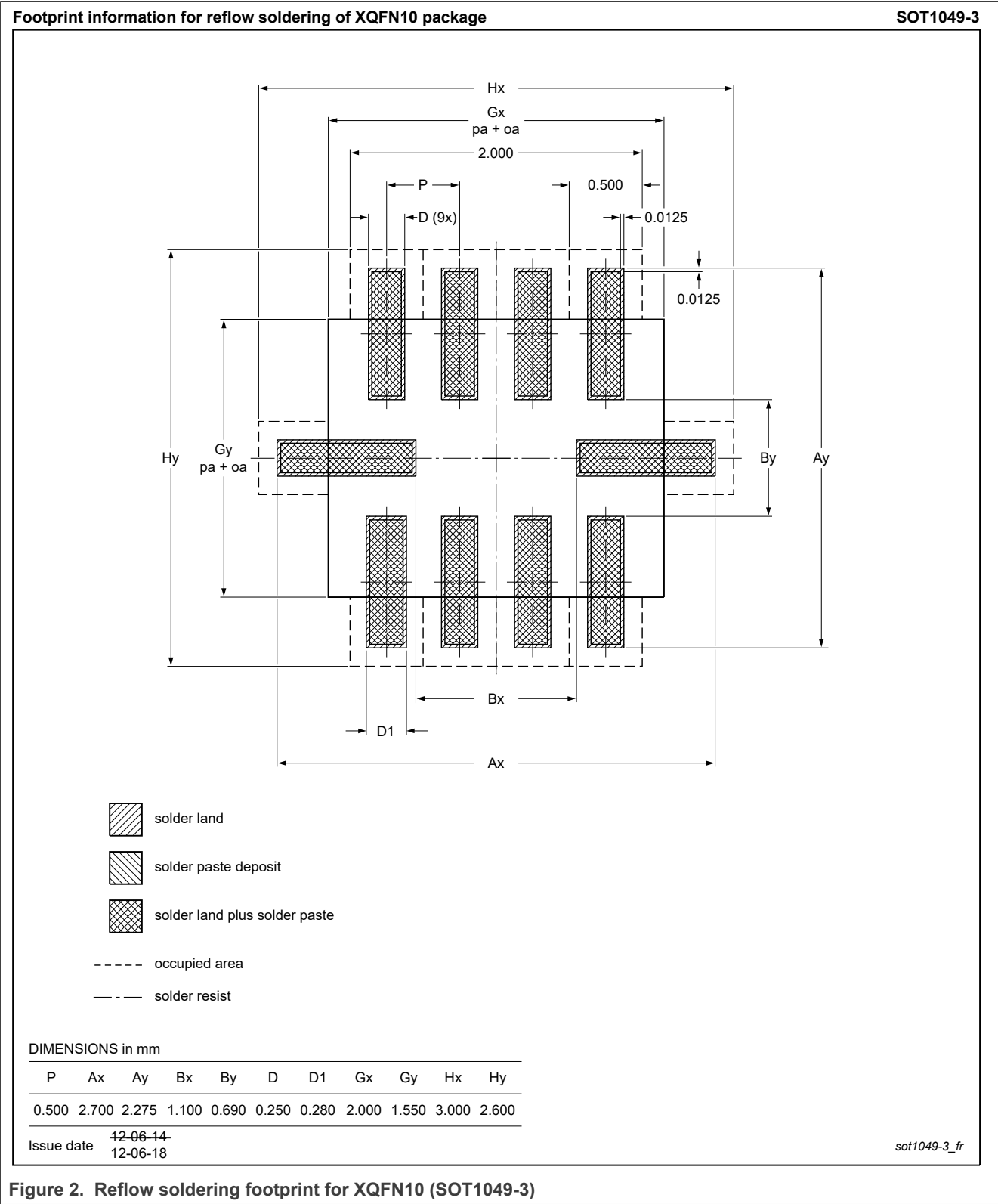


Figure 2. Reflow soldering footprint for XQFN10 (SOT1049-3)

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4 Legal information

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